Modeling Radiation Damage to Pixel Sensors in the *ATLAS* Detector



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Lawrence Berkeley National Laboratory

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ATLAS Pixel Detector

4 pixel layers

Outer three layers

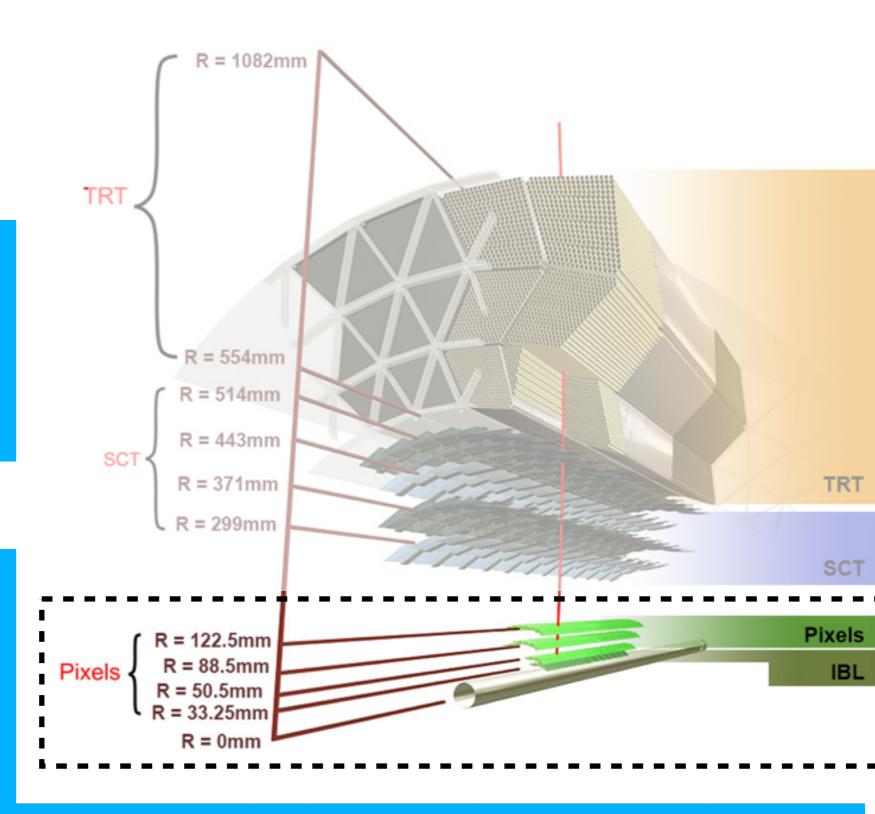
$50 \times 400 \times 250 \ \mu m^3$

FEI3 readout chip (8 bit ToT)

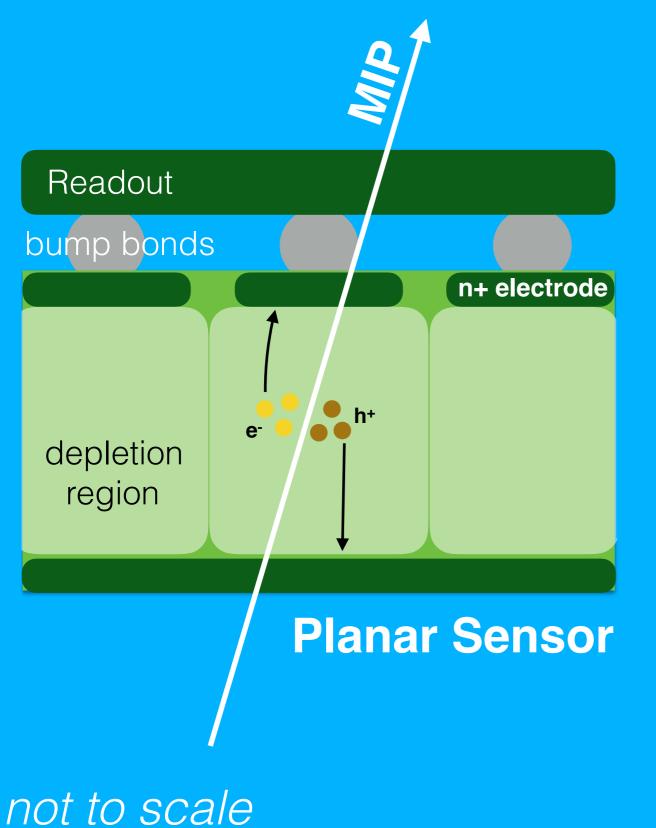
Innermost layer

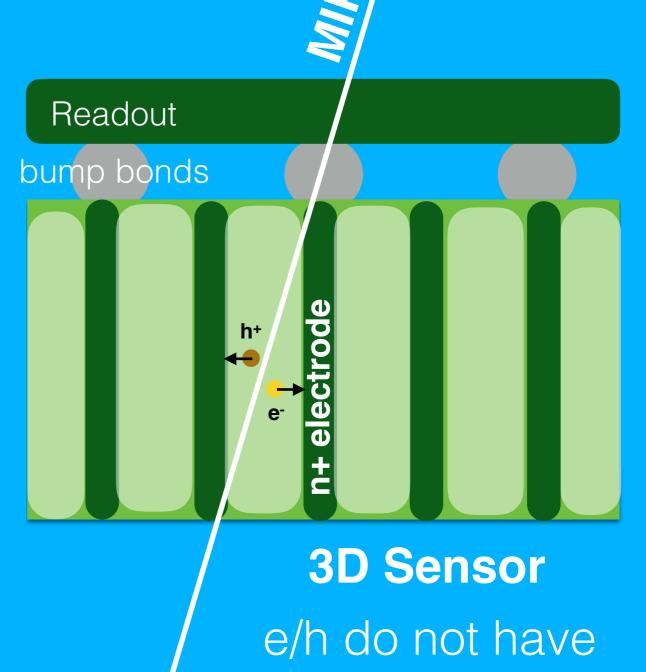
50 x 250 x 200 μm³ FEI4 readout chip (4 bit ToT)





ATLAS Pixel Modules



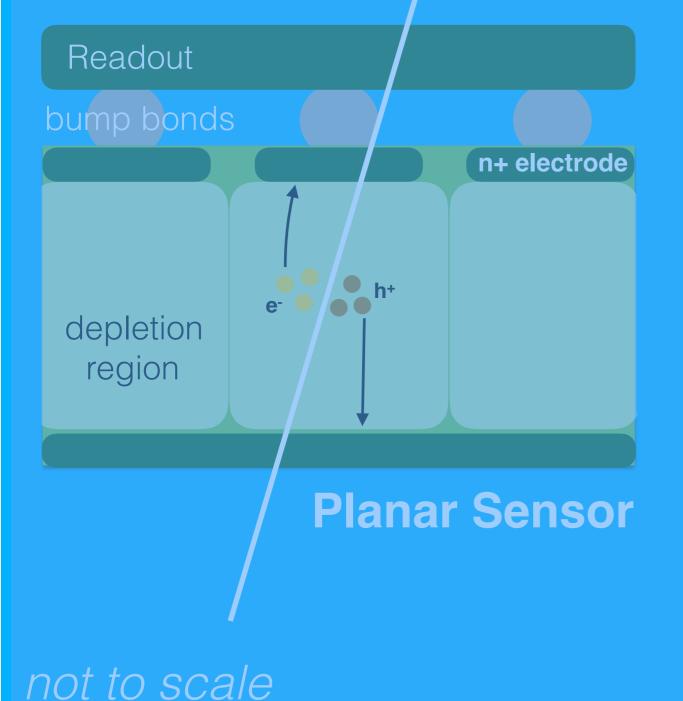


to travel as far

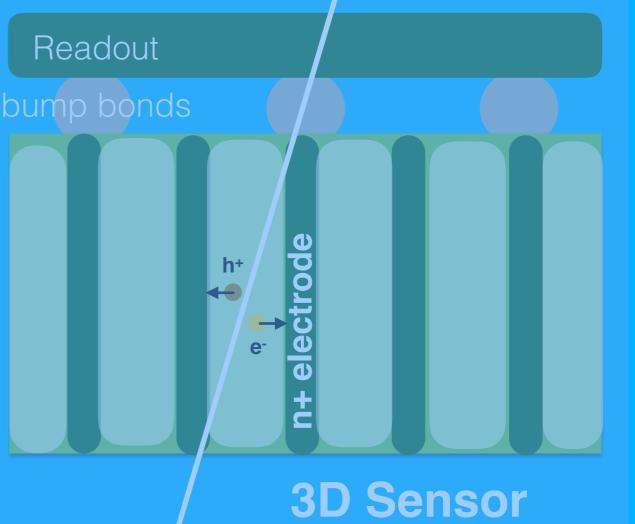
3

ATLAS Pixel Modules

Focus on planar for the rest of the talk

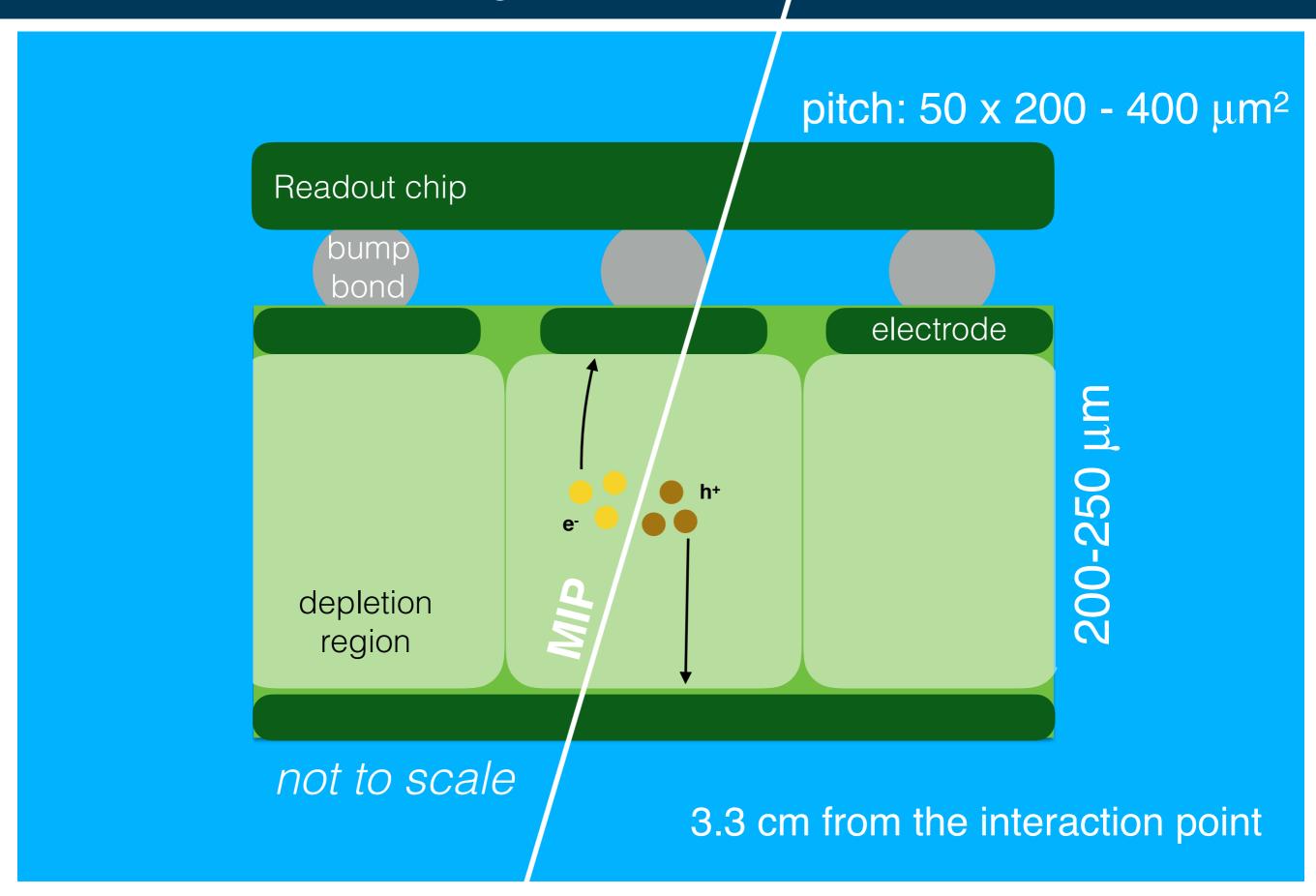


(3D's are ouiside tracking acceptance)



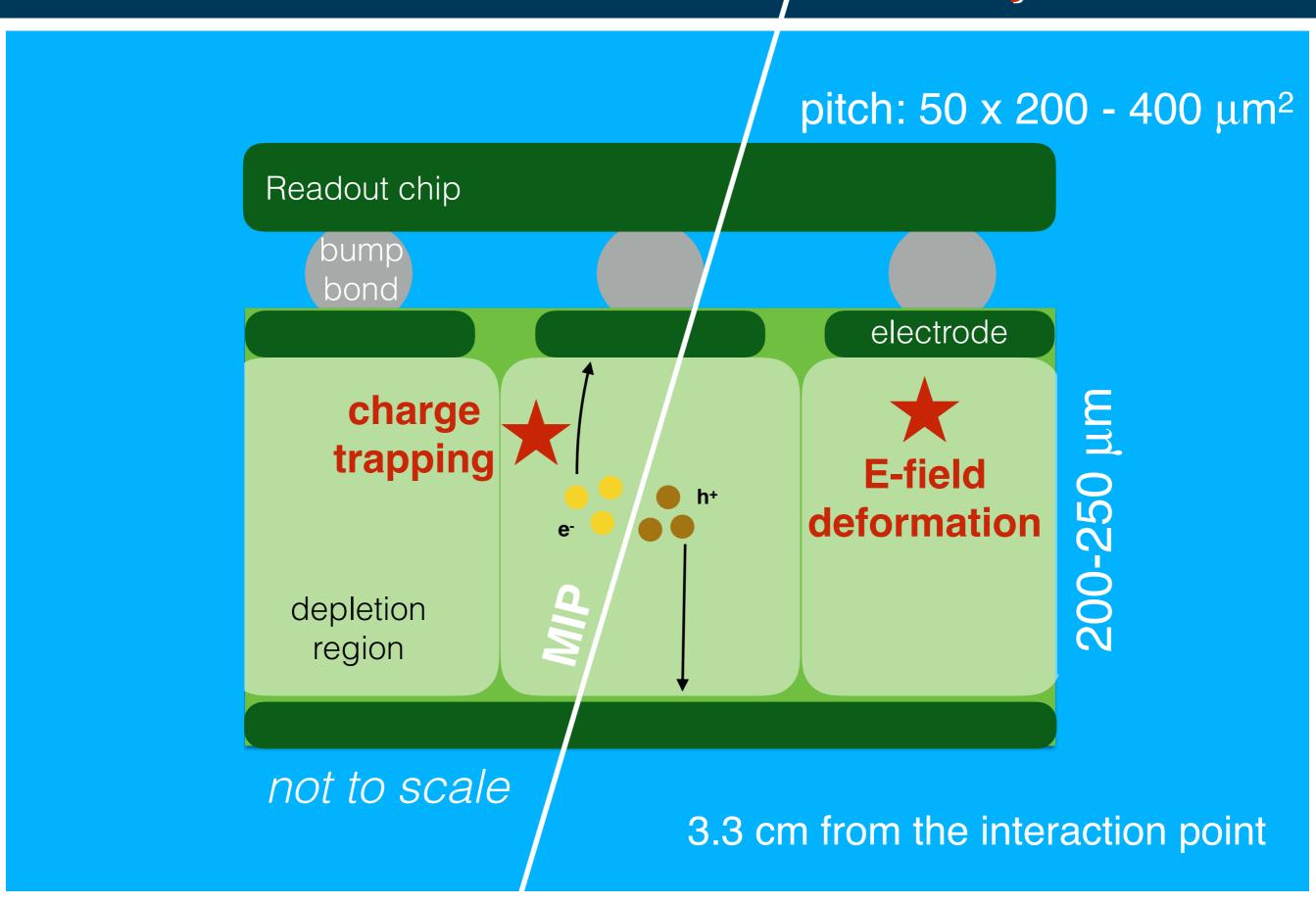
e/h do not have to travel as far

Pixel Radiation Damage

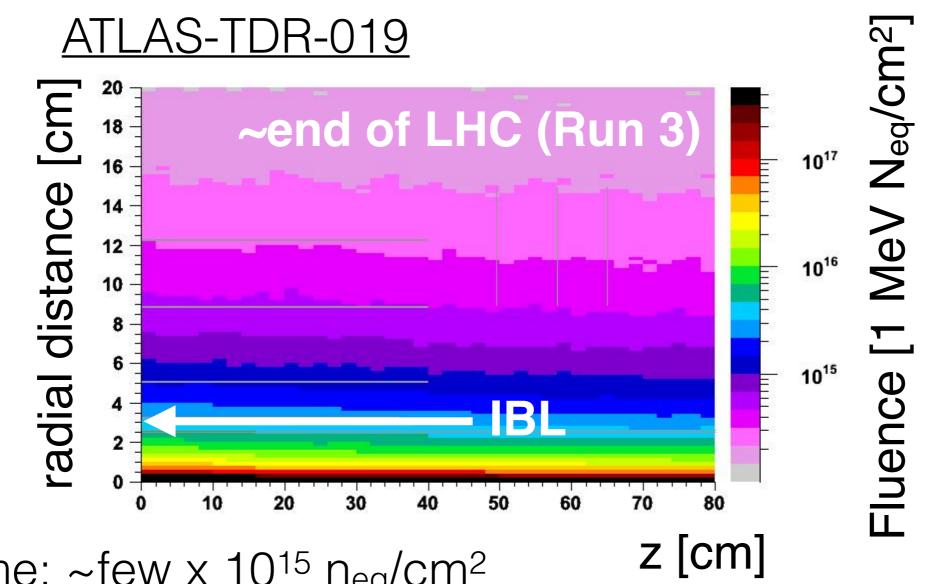


Pixel Radiation Damage → Defects / in the crystal!

6



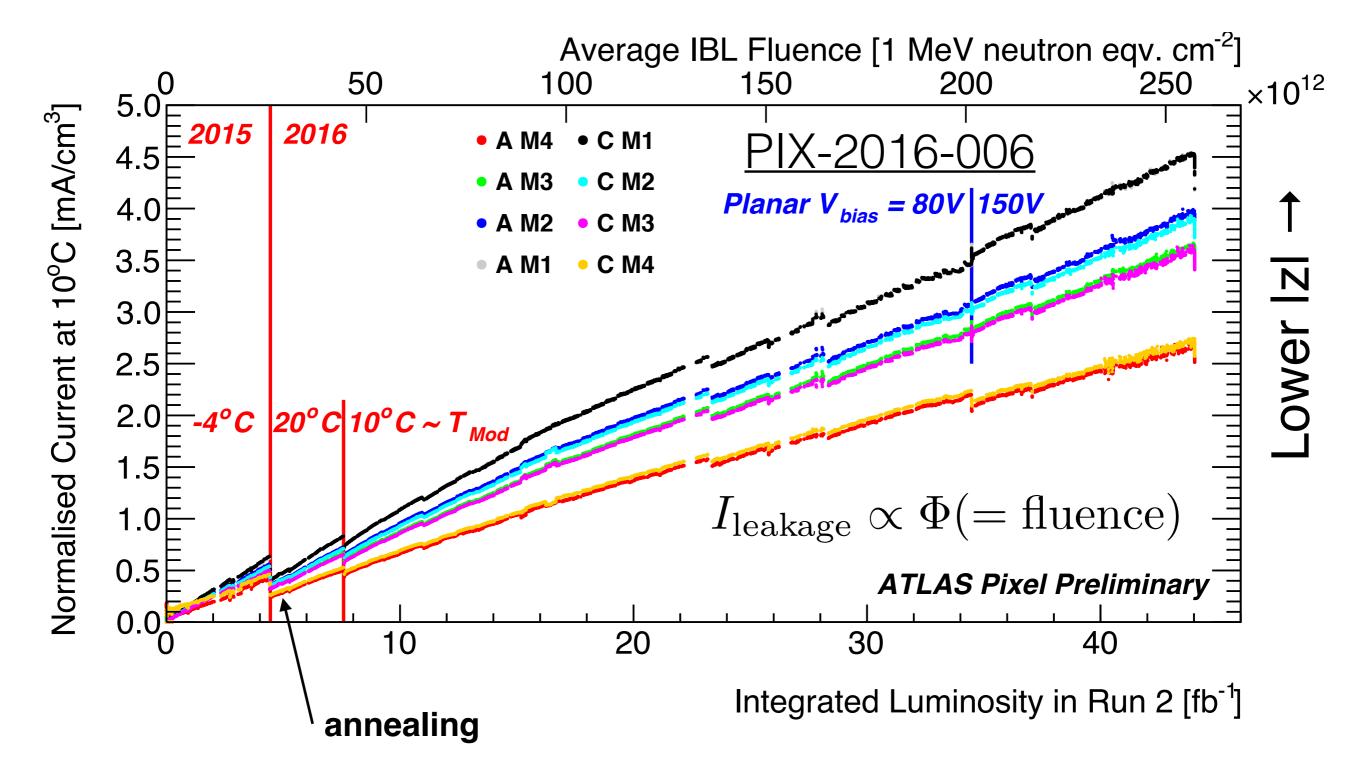
Part I: Monitoring **Radiation Damage Effects**



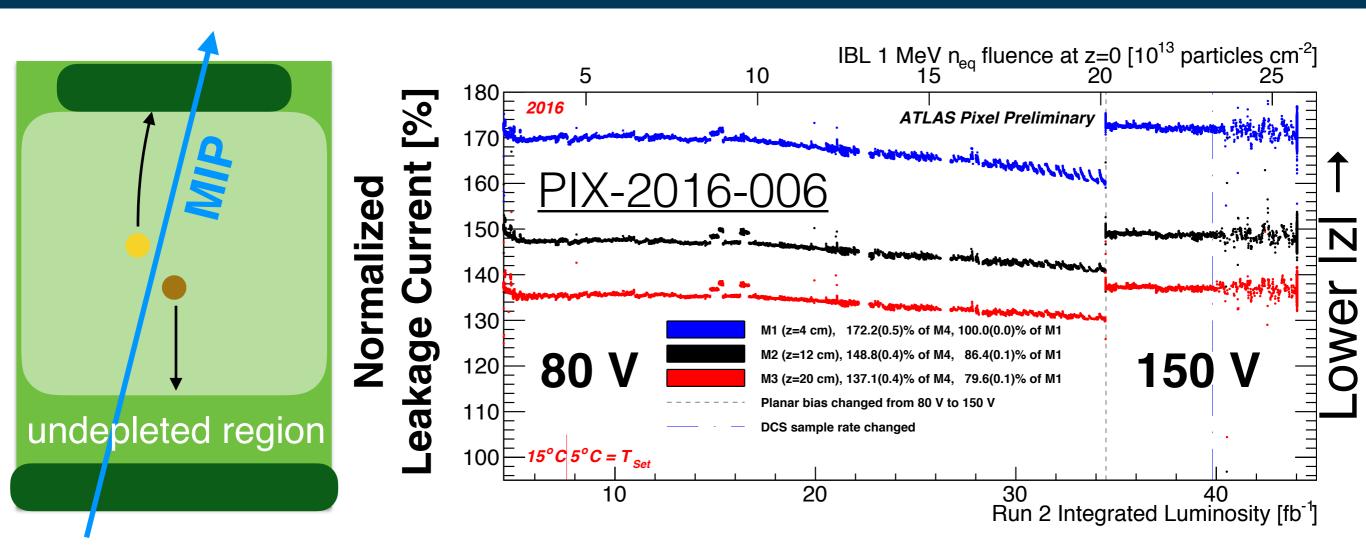
IBL lifetime: ~few x 10¹⁵ n_{eq}/cm²

Leakage Current

→ More defects = more thermal charges = leakage current



Depletion Voltage and Leakage Current



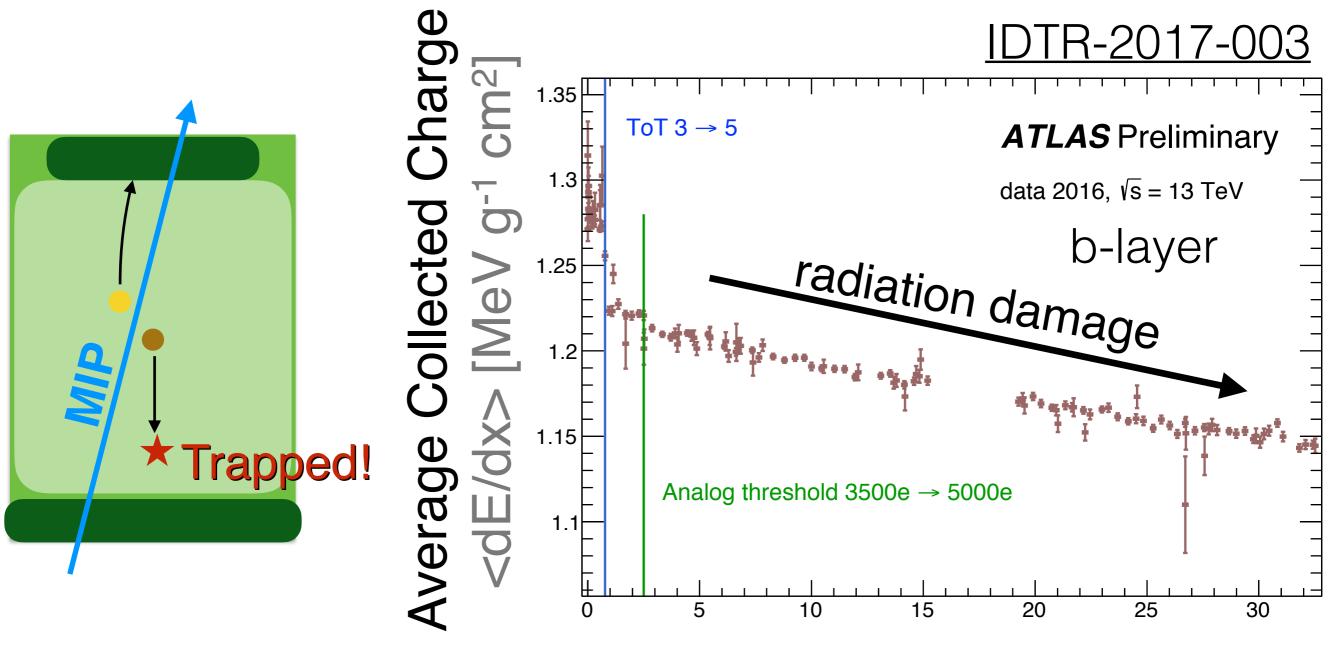
9

Leakage current proportional to fluence; proportionally constant is independent of IzI.

→ leakage current ratios tell us about the depleted volume (normalized to 3D sensors that are always depleted here)

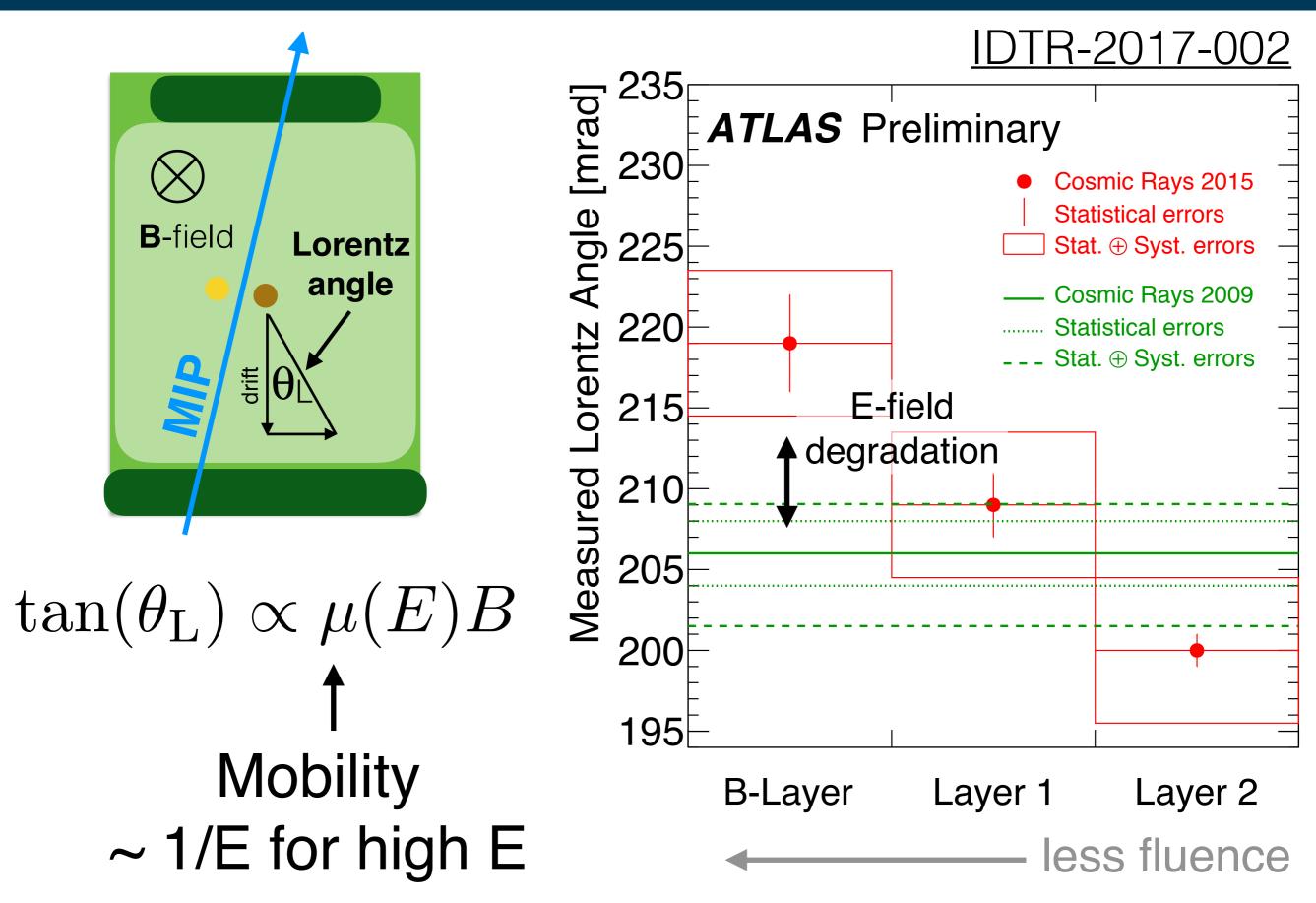
Charge Collection Efficiency

Average charge collected from MIPs decreased due to charge trapping



Integrated Luminosity [fb⁻¹]

Lorentz Angle



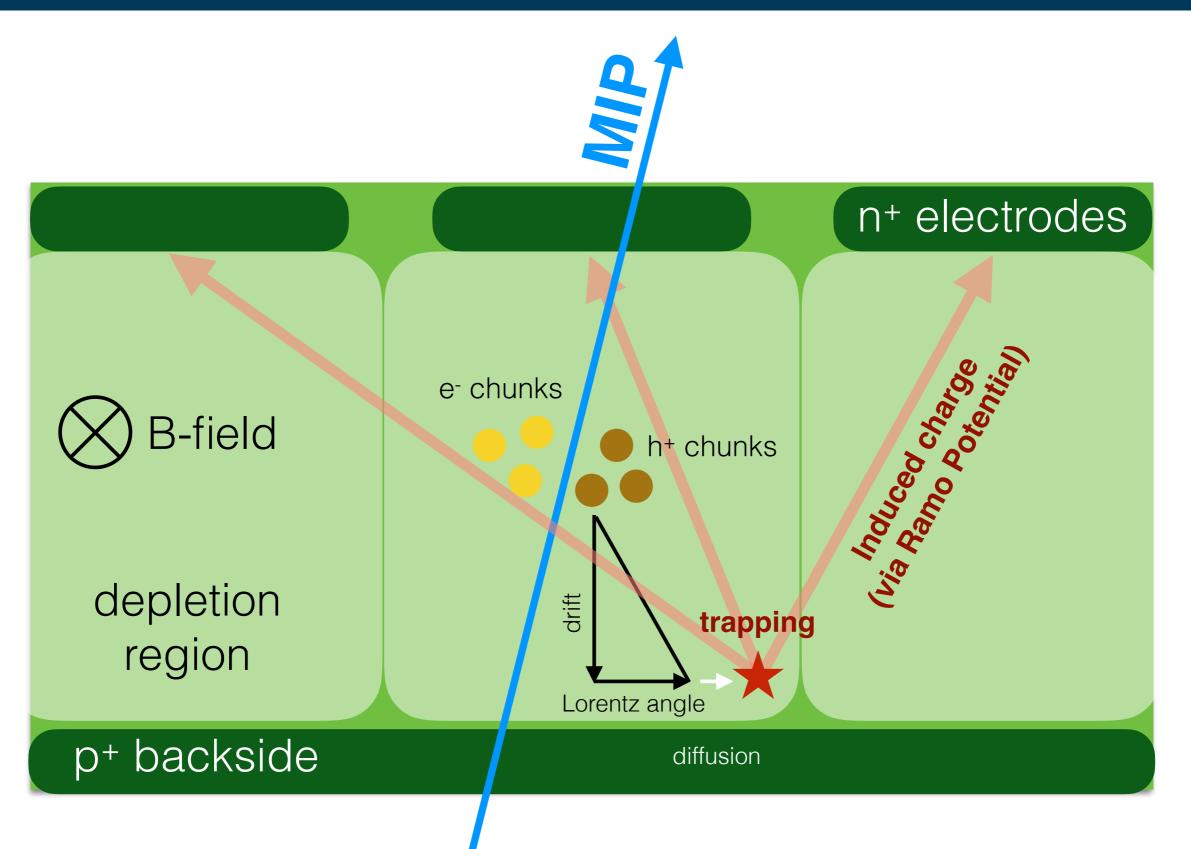
Part II: Modeling Radiation Damage Effects

Radiation damage is already producing measurable effects; this will only continue to be more important.

→ Need to include radiation damage in our simulation!

This is currently not done by default for the current or HL-LHC ATLAS simulations !

ATLAS Pixel Digitization Simulation



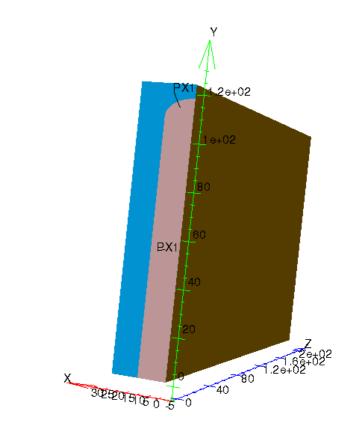
Modeling Electric Field De Structure

Use TCAD to calculate the E-field

2-trap (Chiochia model) for planar and 3-trap (Perugia model) for 3D

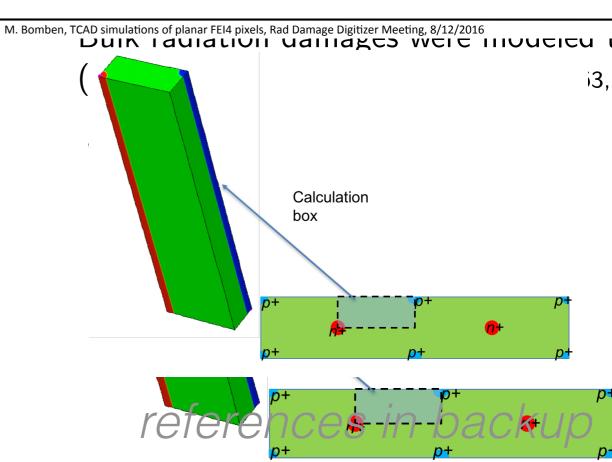
traps are O(k_BT) from the intrinsic energy level

additional parameters: e/h capture cross sections and introduction rates



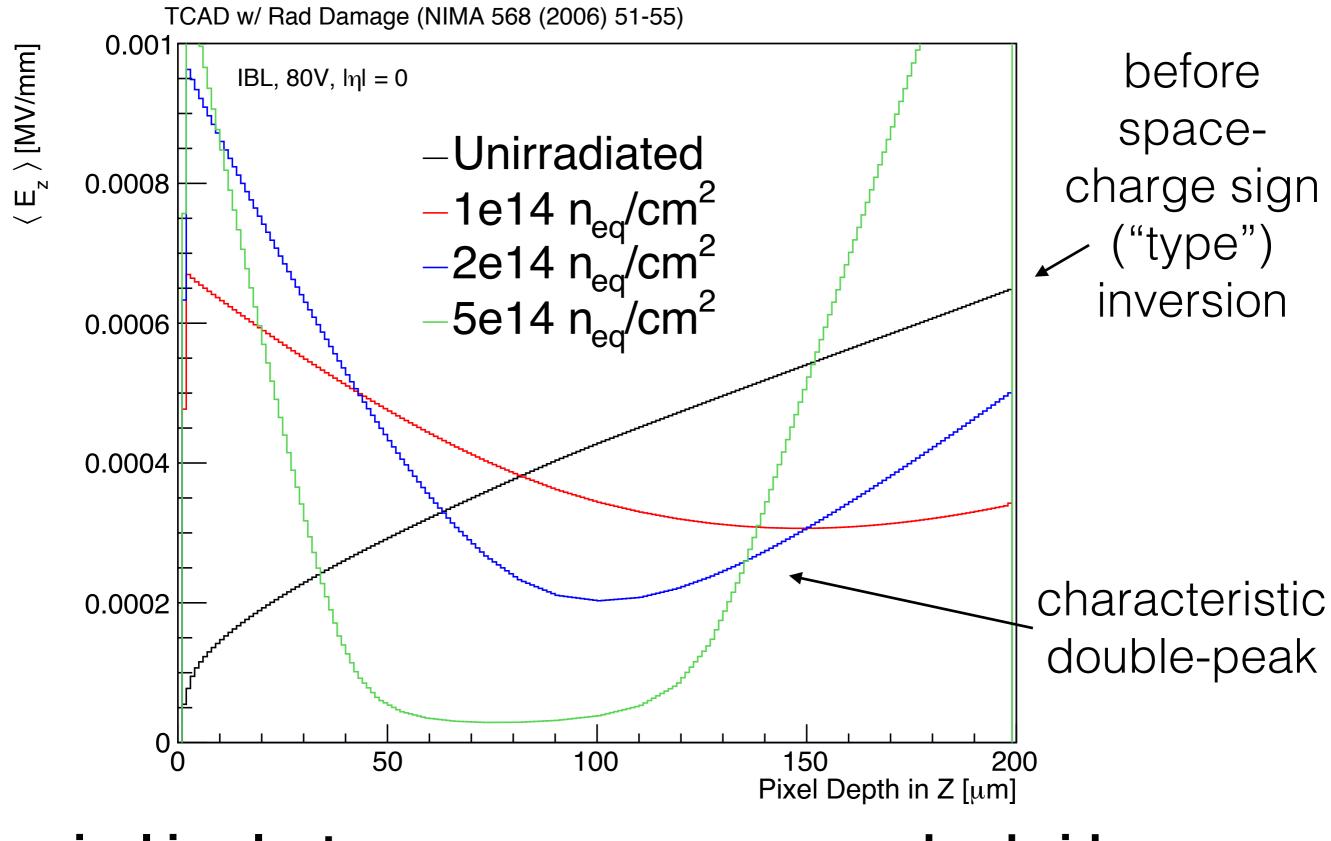
Materials:

Silicon Aluminum SiO2



Electric Field: Field Profiles

IBL planar modules 15

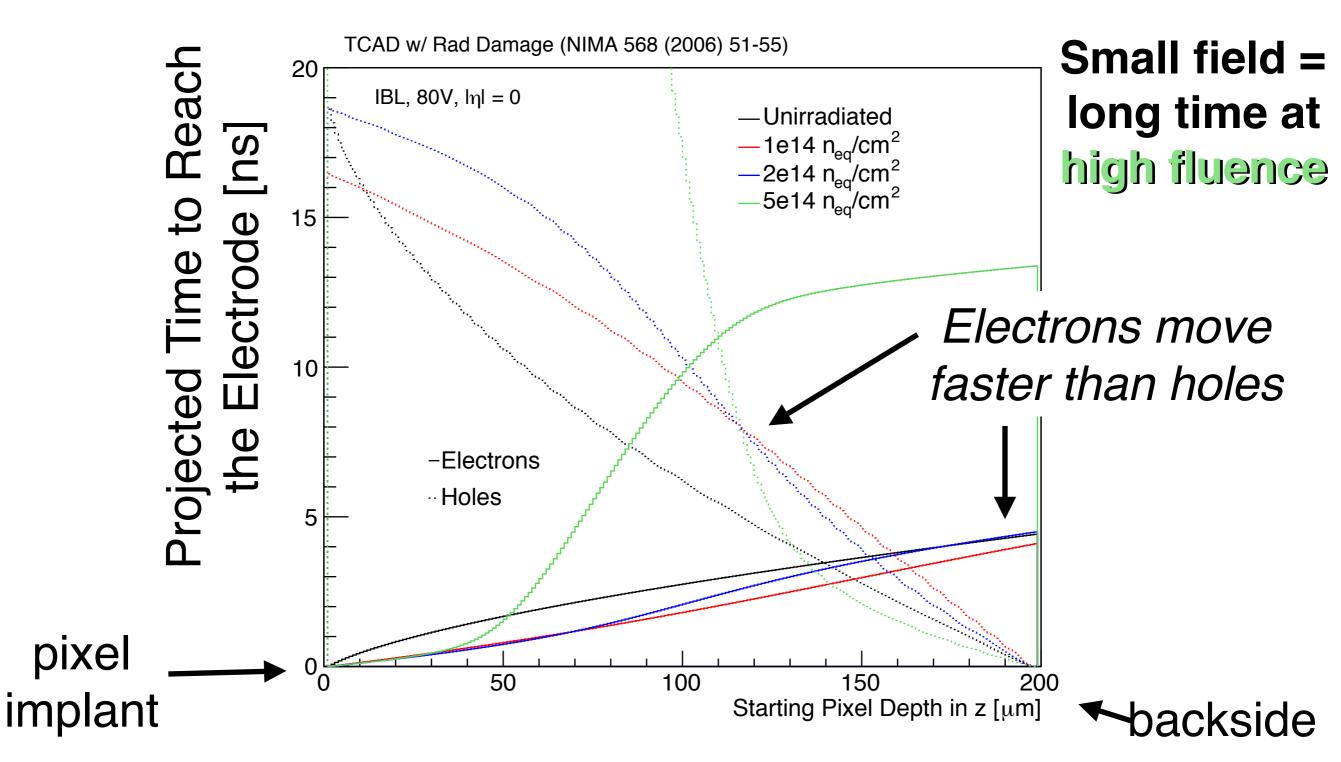


pixel implant

backside

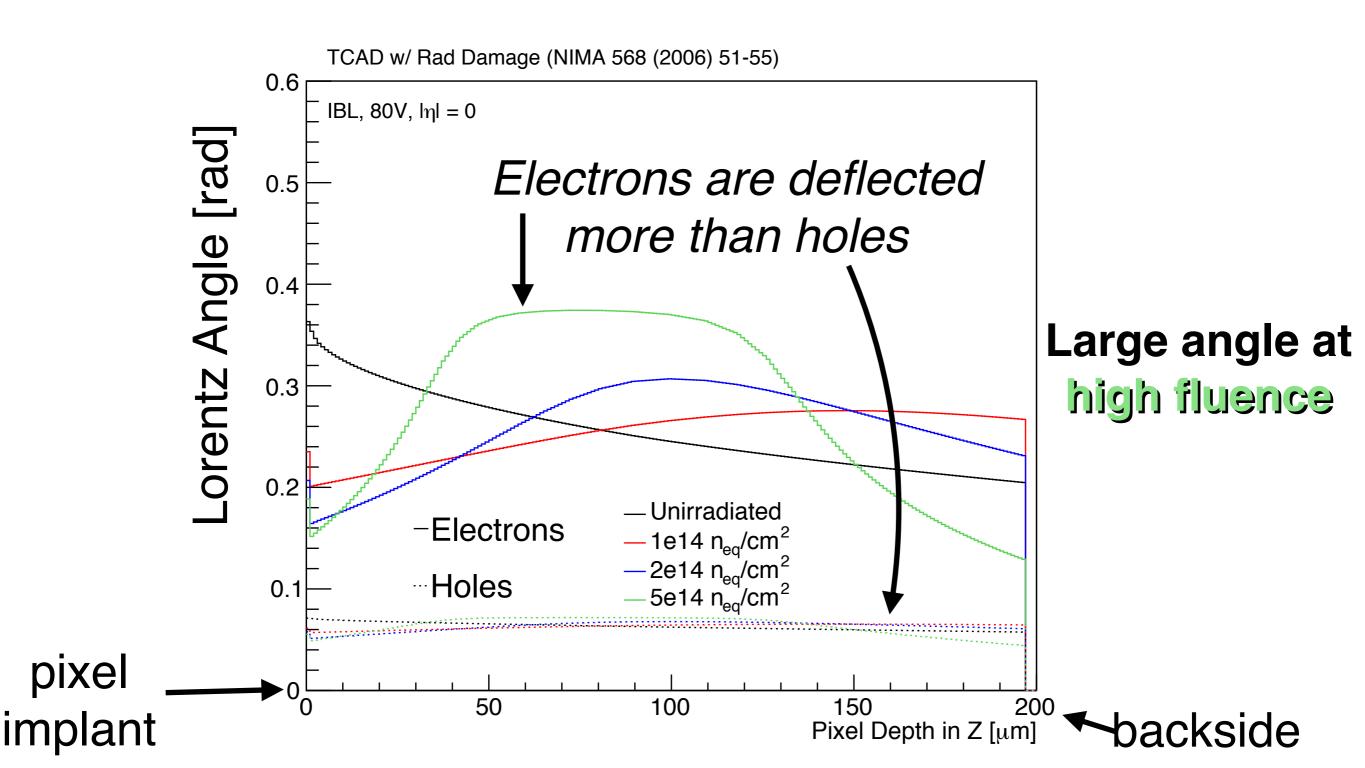
Time-to-electrode

To save time, we pre-compute ('maps') all the quantities derived from the E-field.



Lorentz Angle

The Lorentz angle also changes with depth because of the non-uniform field: $tan(\theta_L) \propto \mu(E)E$

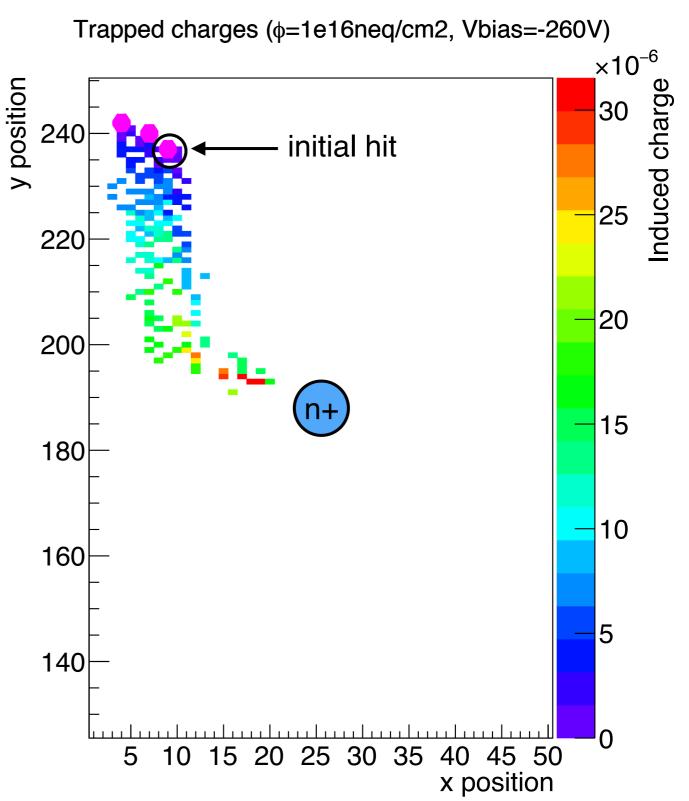


Trapping

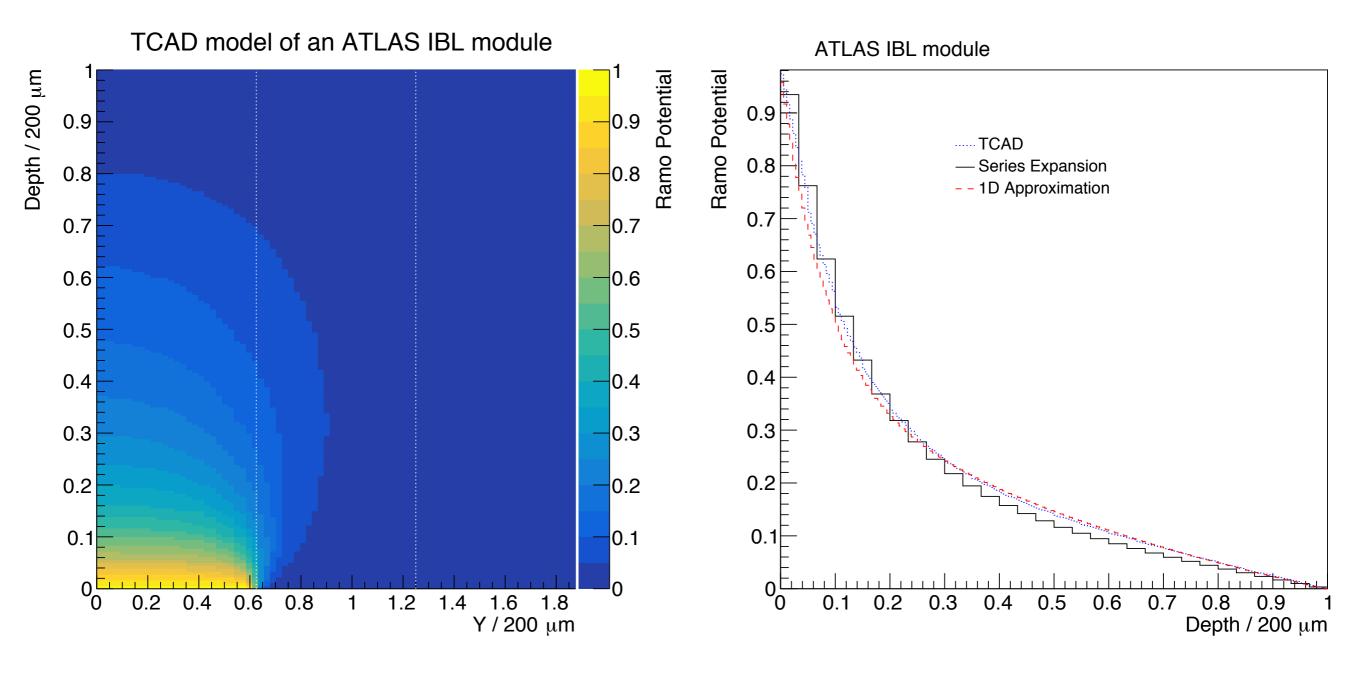
Charged get trapped with a time constant $\tau \sim 1 \text{ ns} @ 3 \times 10^{15} \text{ n}_{eq}/\text{cm}^2$

Even trapped charges contribute to the signal, calculated with the Ramo potential (\$)

$$Q_{\text{induced}} = -Q[\phi(\vec{x}_{\text{end}}) - \phi(\vec{x}_{\text{start}})]$$

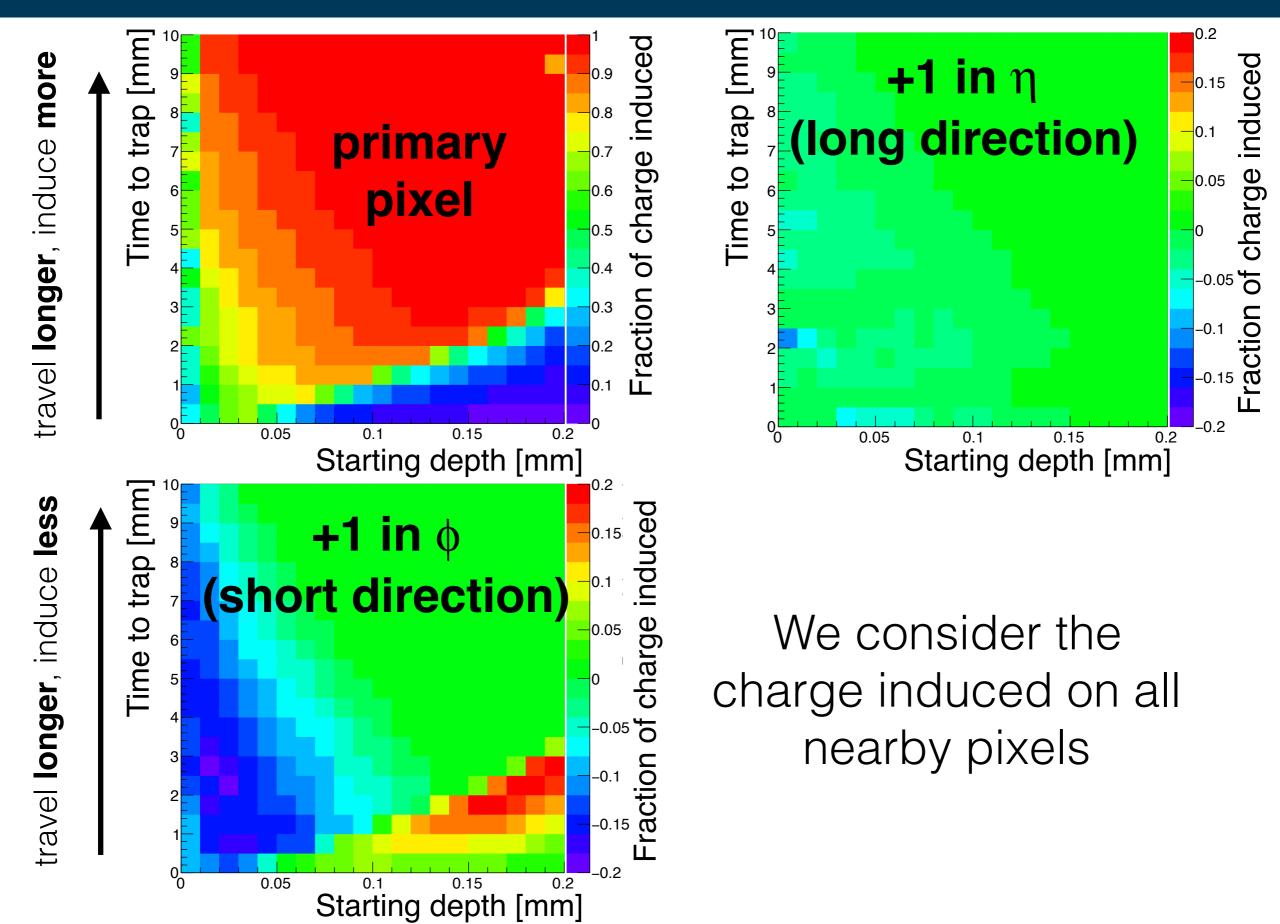


Ramo Potential

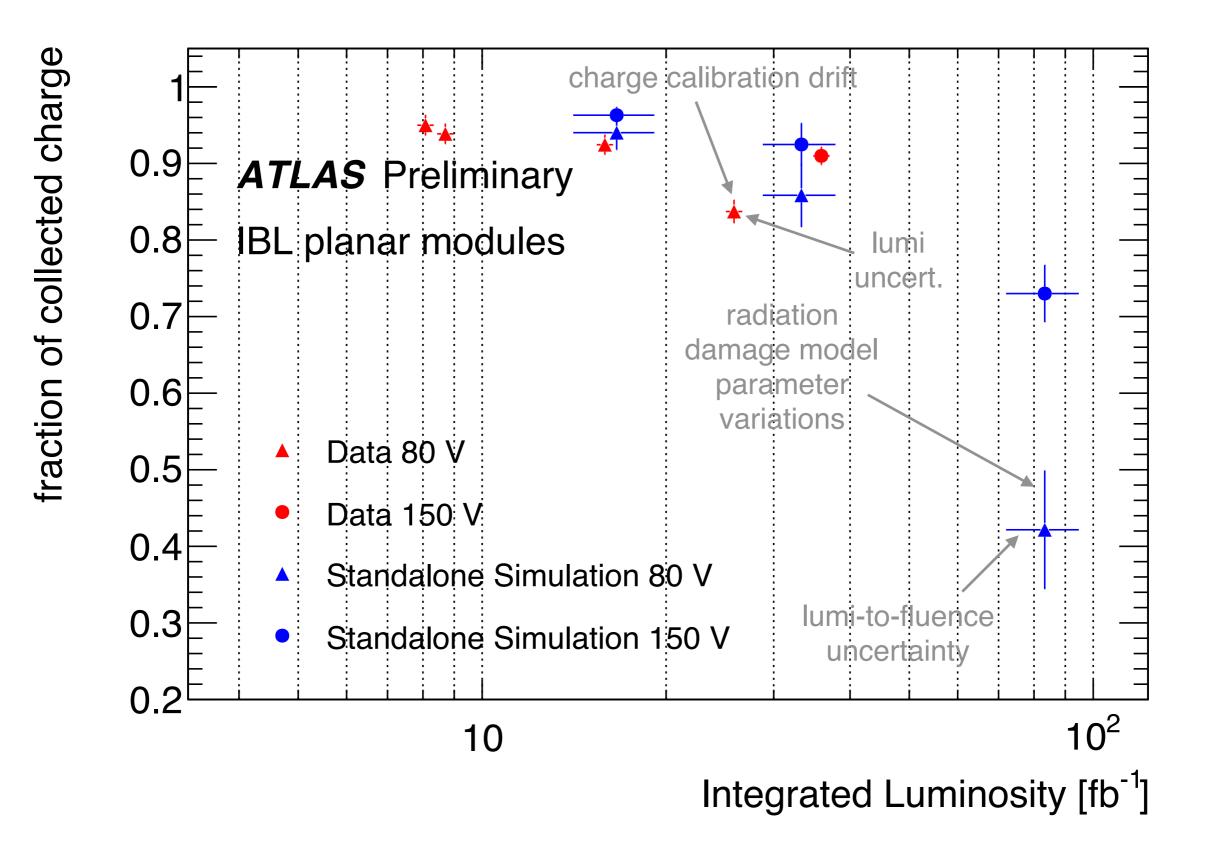


1 @ electrode, 0 @ far away

Ramo Potential - Induced Charge IBL planar modules 20



Model Prediction and Comparison with Data 21

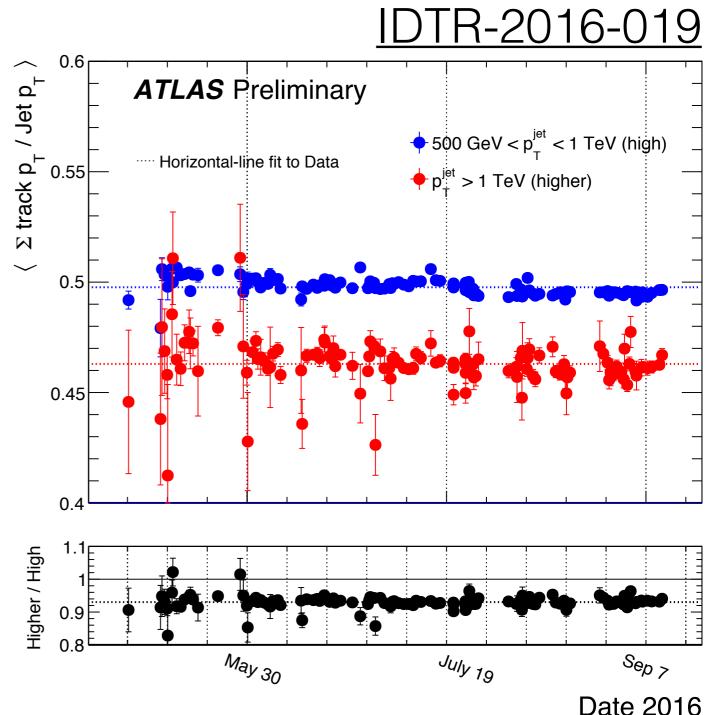


Conclusions and Future Outlook

We have developed pixel digitization model with radiation damage effects.

Tracking performance seems insensitive to the present fluence levels, but **degradation is inevitable**

We are now prepared to model the degradation for Run 2+3 and for the HL-LHC







The LHC-LHC is on the horizon ... are you ready? [1] Marco Bomben et al., Planar TCAD Simulation Details

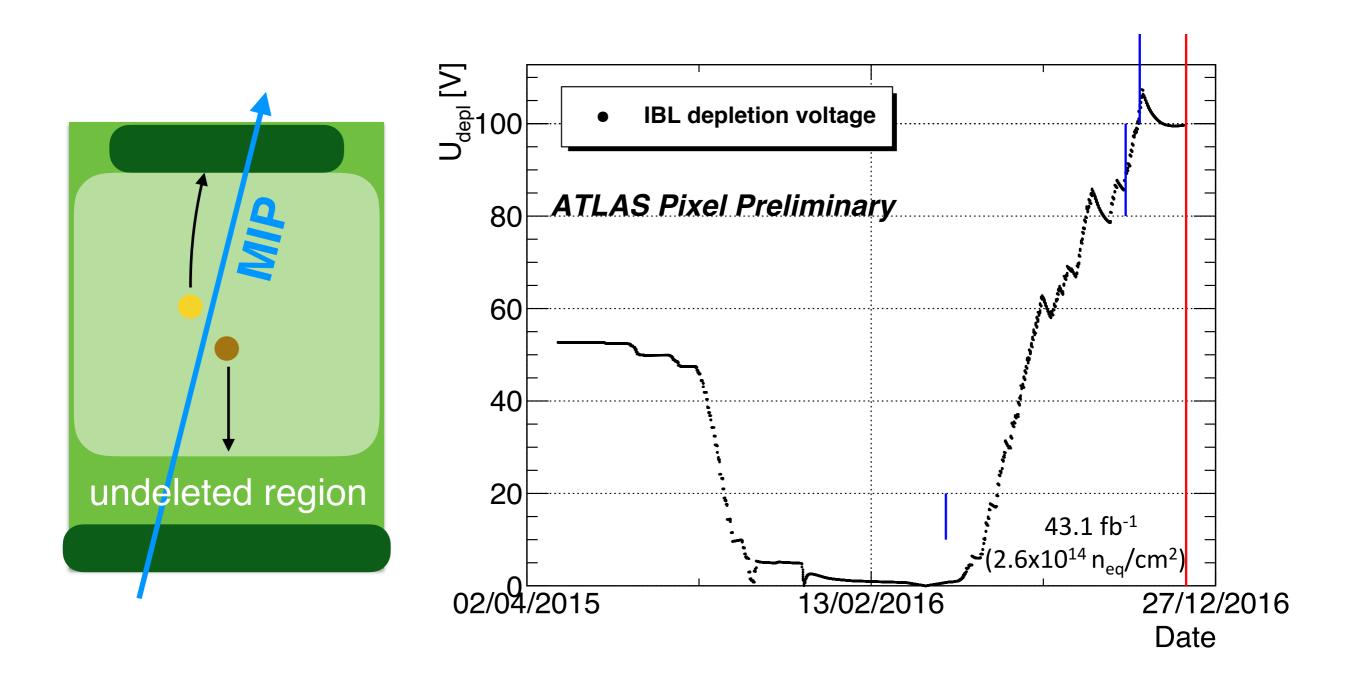
[2] Gilberto Giugliarelli et al., <u>3D TCAD Simulation Details</u>



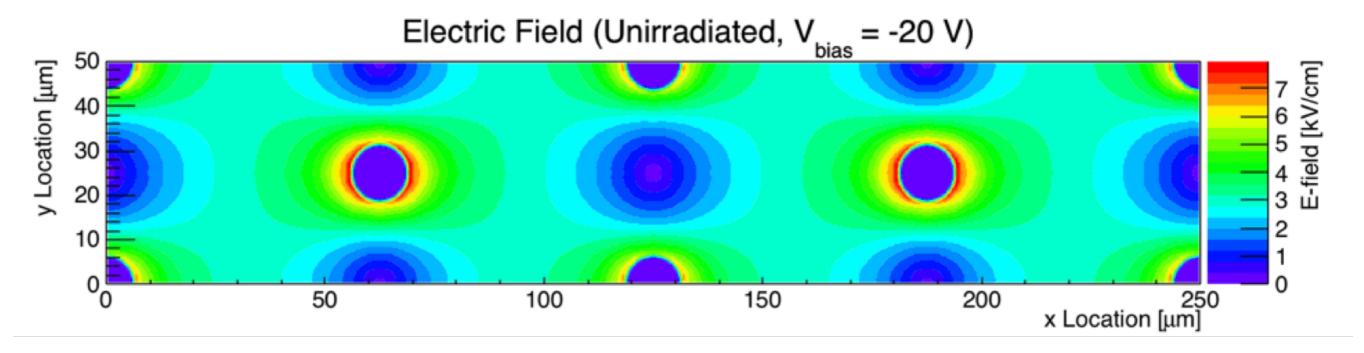
Slide Change After Presentation

p10 was slightly modified to reflect the fact that the HV was changed in the IBL and not the b-layer towards the end of the run. The b-layer was fully depleted during all of 2016.

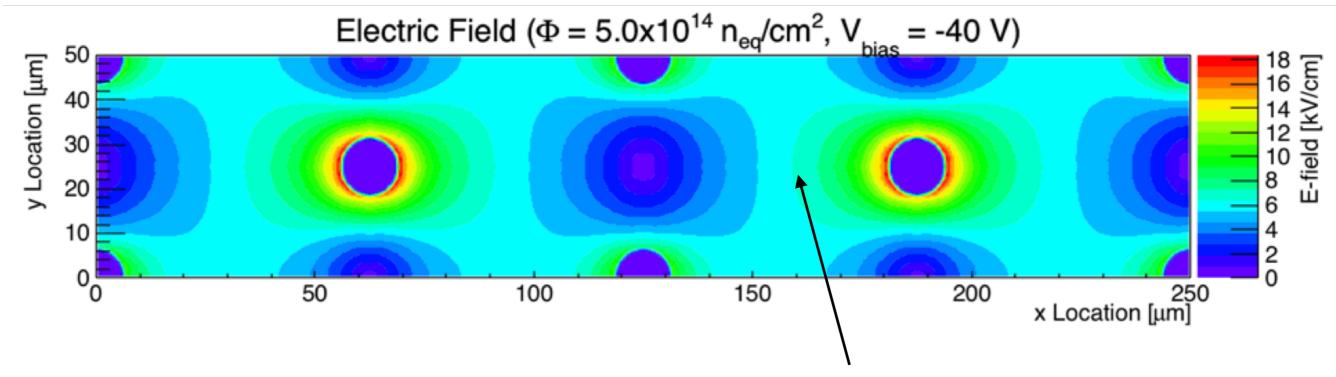
Depletion Voltage - Predictions



Electric Field: Field Profiles



150 20 Pixel Depth in Z [μm]



no double peak, but field is weaker